

Patent Abstracts of Japan

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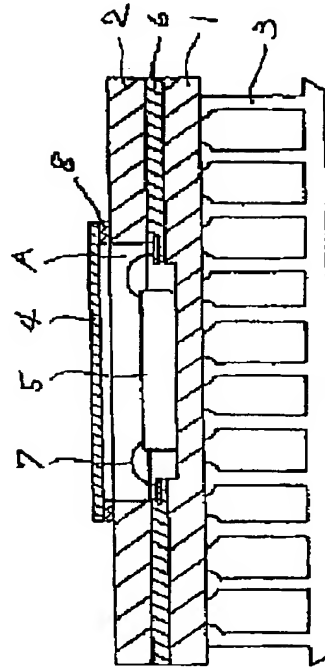
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APPLICANT : KYOCERA CORP;

INVENTOR : ITO YOSHIKI;

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TITLE : GLASS SEALED SEMICONDUCTOR  
ELEMENT CONTAINING PACKAGE



ABSTRACT : PURPOSE: To provide the title glass sealed semiconductor element containing package capable of actuating the contained semiconductor element normally and stably.

CONSTITUTION: Within the title glass sealed semiconductor element containing package wherein an outer lead 3 is fixed between an insulating substrate 1 and a frame body 2 by a fixing glass member 6, furthermore, the frame body 2 and a cover body 4 are junctioned with each other by a sealing glass member 8, the sealing glass member 8 is formed of a glass of low softening and melting temperature containing 42.0-52.0Wt% of lead oxide, 15.0-25.0Wt% of vanadium oxide, 2.0-8.0Wt% of tellurium oxide, 0.5-2.0Wt% of zinc oxide as well as 15.0-25.0Wt% of tin-titanium oxide as a filler. Through these procedures, when the frame body 2 and the cover body 4 are joined with each other using the sealing glass member 8, the water content discharged from the fixing glass member 6 can be minimized resultantly minimizing the water content inside the package, thereby enabling the semiconductor element to be normally actuated.

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